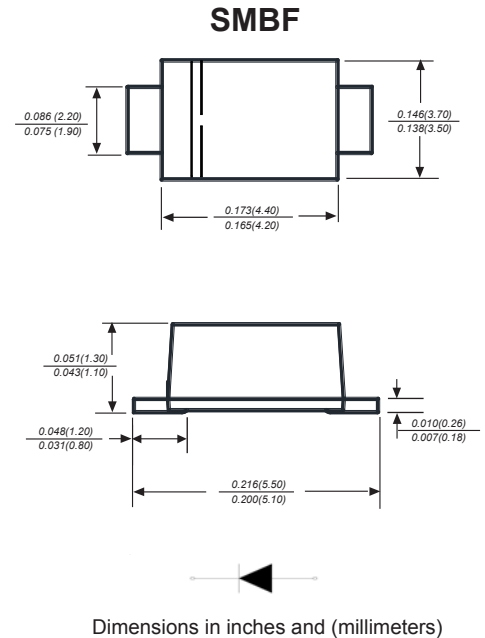


Features

1. Metal silicon junction, majority carrier conduction For surface mounted applications
2. Low power loss,high efficiency
3. High forward surge current capability
4. For use in low voltage,high frequency inverters, free wheeling,and polarity protection applicatons

Mechanical Data

Case :JEDEC SMBF molded plastic body
 Terminals : Solderable per MIL-STD-750,Method 2026
 Polarity : Polarity symbol marking on body
 Mounting Position : Any
 Weight : 0.002 ounce, 0.057 grams



Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unlls otherwise specified.

Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS32BF	SS33BF	SS34BF	SS35BF	SS36BF	SS38BF	SS310BF	SS315BF	SS320BF	UNITS
Marking Code		SS32BF	SS33BF	SS34BF	SS35BF	SS36BF	SS38BF	SS310BF	SS315BF	SS320BF	
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V
Maximum average forward rectified current at TL(see fig.1)	$I_{(AV)}$	3.0									A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	80					70				A
Maximum instantaneous forward voltage at 3.0A	V_F	0.55			0.70		0.85		0.95		V
Maximum DC reverse current $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	I_R	0.5					0.3				mA
		5.0					3.0				
Typical junction capacitance (NOTE 1)	C_J	450					400				pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	50.0									$^{\circ}C/W$
Operating junction temperature range	T_J	-55 to +125									$^{\circ}C$
Storage temperature range	T_{STG}	-55 to +150									$^{\circ}C$

Note: 1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

Typical Characteristics

Fig.1 Forward Current Derating Curve

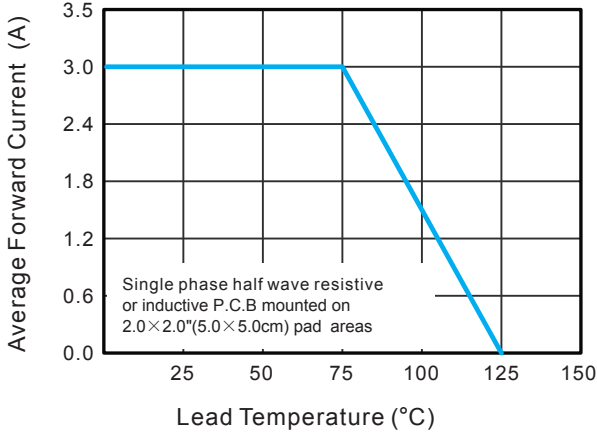


Fig.2 Typical Reverse Characteristics

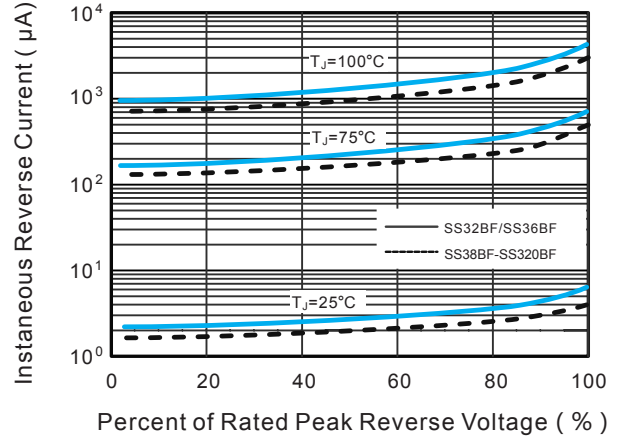


Fig.3 Typical Forward Characteristic

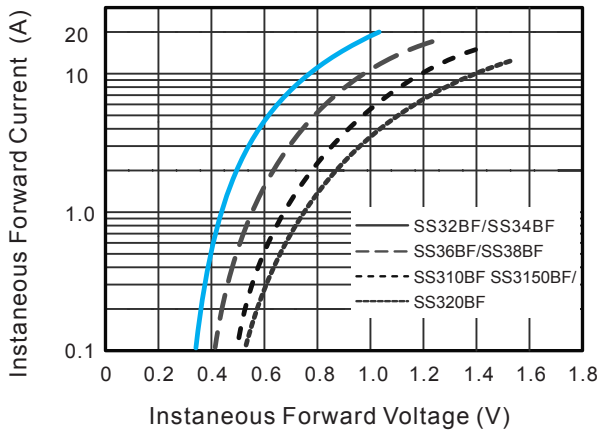


Fig.4 Typical Junction Capacitance

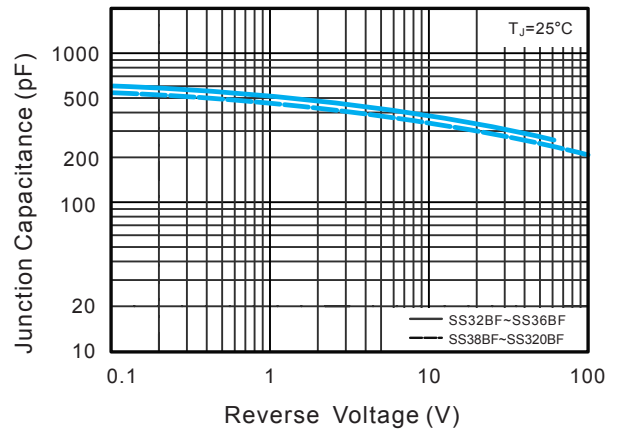


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

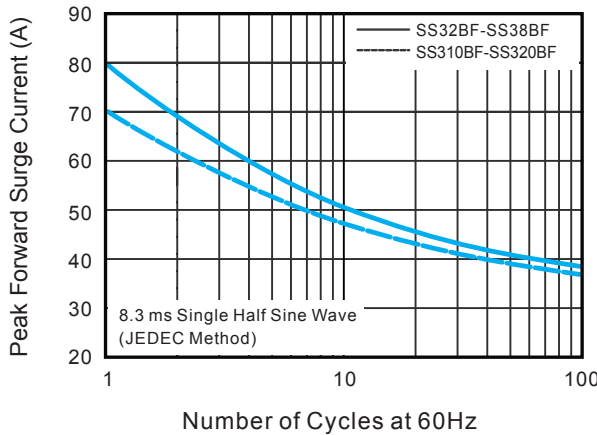
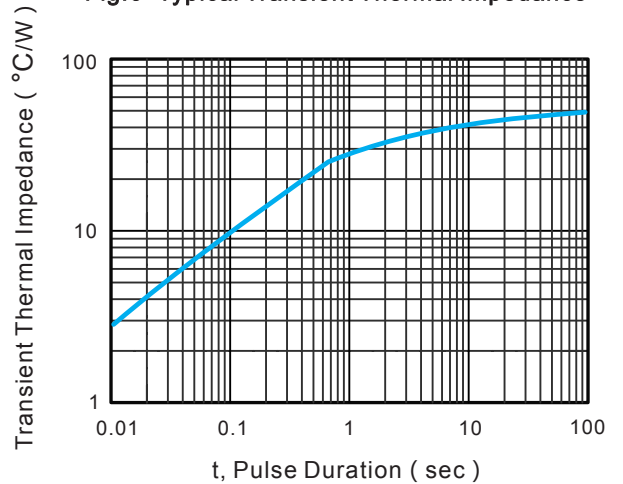
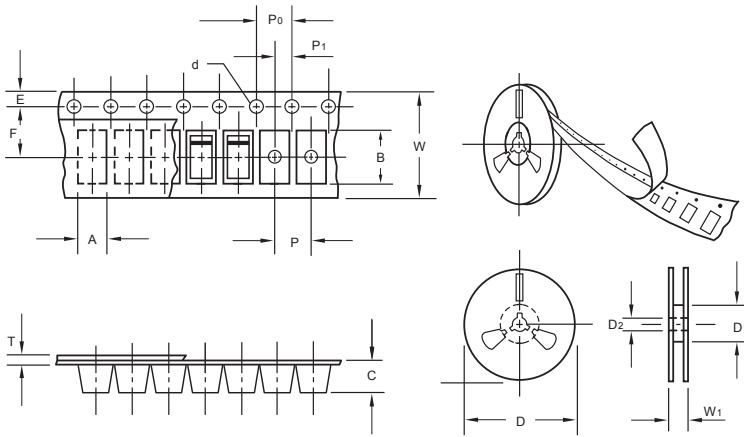


Fig.6- Typical Transient Thermal Impedance



Packing information



unit:mm

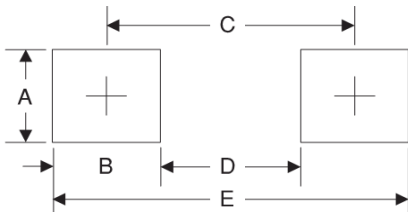
Item	Symbol	Tolerance	SMBF
Carrier width	A	0.1	3.81
Carrier length	B	0.1	5.61
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W1	1.0	12.30

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (mm)	BOX (pcs)	INNER BOX (mm)	REEL DIA, (mm)	CARTON SIZE (mm)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMBF	13"	5,000	4.0	10,000	190*190*41	330	365*365*360	80,000	14.0

Suggested Pad Layout



Symbol	Unit (mm)	Unit (inch)
A	2.54	0.100
B	1.8	0.071
C	4.8	0.189
D	3.0	0.118
E	6.6	0.260